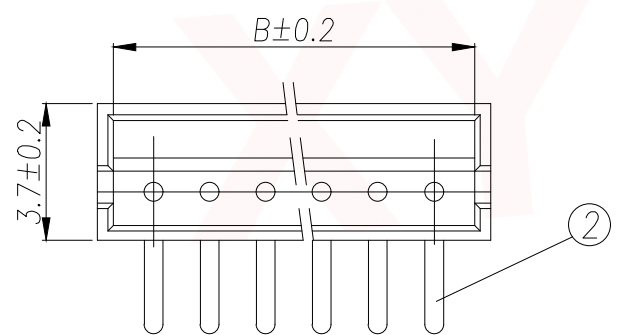
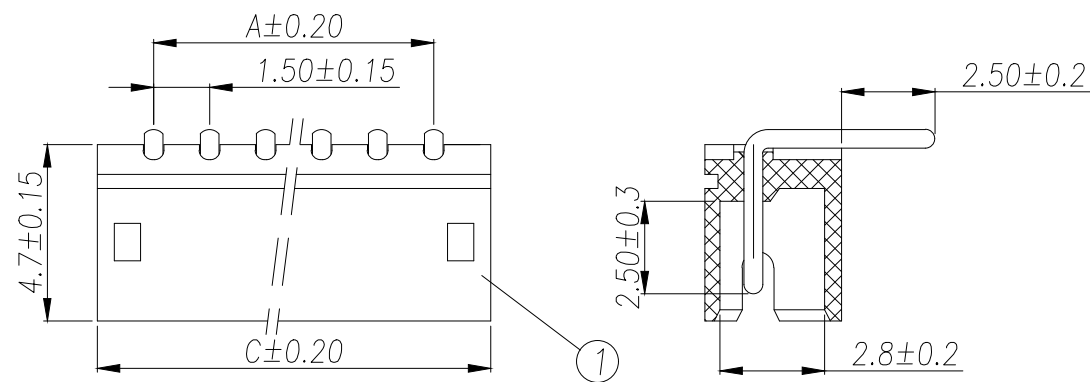


REV.	Q'TY	ECN. NO.	APR.	DATE

PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



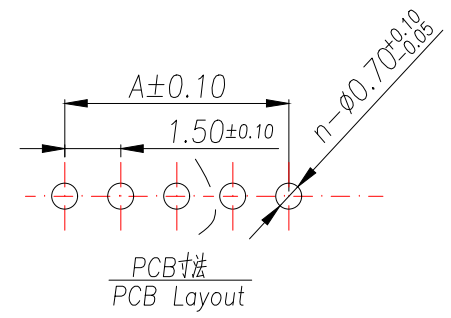
ROHS管理规定:

1. 禁止使用含有ROHS指令所限制的物质。
2. 对应的SGS或ITS出具的ICP-AES数据, 不可测定物质的成分表, 有效期一年。

技术指标:

1. 塑件表面应光洁, 无毛刺, 明显收缩, 缺陷, 裂纹等现象;
2. 温度范围: -25°C~85°C;
3. 额定电压: 250V, AC, DC(等效);
4. 接触电阻: $\leq 0.03\Omega$;
5. 绝缘电阻: >math>\geq 1000M\Omega</math>;
6. 耐压: 1000V, AC/minute.

Part No	PIN	A	B	C
XY-ZH1.5-2A21	2	1.5	3.6	4.5
XY-ZH1.5-3A21	3	3	5.1	6
XY-ZH1.5-4A21	4	4.5	6.6	7.5
XY-ZH1.5-5A21	5	6	8.1	9
XY-ZH1.5-6A21	6	7.5	9.6	10.5
XY-ZH1.5-7A21	7	9	11.1	12
XY-ZH1.5-8A21	8	10.5	12.6	13.5
XY-ZH1.5-9A21	9	12	14.1	15
XY-ZH1.5-10A21	10	13.5	15.6	16.5
XY-ZH1.5-11A21	11	15	17.1	18
XY-ZH1.5-12A21	12	16.5	18.6	19.5
XY-ZH1.5-13A21	13	18	20.1	21
XY-ZH1.5-14A21	14	19.5	21.6	22.5
XY-ZH1.5-15A21	15	21	23.1	24
XY-ZH1.5-16A21	16	22.5	24.6	25.5



2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

厦门市辛译精密电子有限公司
Xiamen XinYi Xyconn Electronics Co.,Ltd

DIMENSION IN mm		TOLERANCE UNLESS OTHERWISE SPECIFIED		APR. Alex		TITLE: WAFER 1.5mm H4.9mm 90°DIP	
.X±0.35	X.*± 5°	CHK. Jack	DWG NO. XY-ZH1.5-NA21	PROJ. CUSTOMER DRAWING			
.XX±0.25	.X.*± 3°	DRA. Can	SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	